

N-Channel Enhancement Mode Power MOSFET

Description

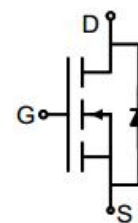
The GT080N10M uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

General Features

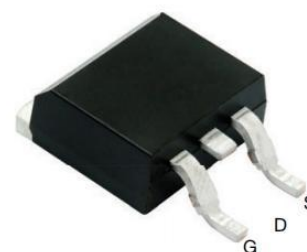
- V_{DS} 100V
- I_D (at $V_{GS} = 10V$) 70A
- $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 8m Ω
- $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 9.5m Ω
- 100% Avalanche Tested
- RoHS Compliant

Application

- Power switch
- DC/DC converters



Schematic diagram



TO-263

Ordering Information

| Device | Package | Marking | Packaging |
|-----------|---------|----------|-------------|
| GT080N10M | TO-263 | GT080N10 | 800pcs/Reel |

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Value | Unit |
|--|----------------|------------|------------------|
| Drain-Source Voltage | V_{DS} | 100 | V |
| Continuous Drain Current | I_D | 70 | A |
| Pulsed Drain Current (note1) | I_{DM} | 280 | A |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Power Dissipation | P_D | 100 | W |
| Single pulse avalanche energy (note2) | E_{AS} | 144 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 To 150 | $^\circ\text{C}$ |

Thermal Resistance

| Parameter | Symbol | Value | Unit |
|---|------------|-------|--------------------|
| Thermal Resistance, Junction-to-Ambient | R_{thJA} | 50 | $^\circ\text{C/W}$ |
| Maximum Junction-to-Case | R_{thJC} | 1.25 | $^\circ\text{C/W}$ |

| Specifications T _J = 25°C, unless otherwise noted | | | | | | |
|--|----------------------|--|-------|------|------|------|
| Parameter | Symbol | Test Conditions | Value | | | Unit |
| | | | Min. | Typ. | Max. | |
| Static Parameters | | | | | | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} = 0V, I _D = 250μA | 100 | -- | -- | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 100V, V _{GS} = 0V | -- | -- | 1 | μA |
| Gate-Source Leakage | I _{GSS} | V _{GS} = ±20V | -- | -- | ±100 | nA |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250μA | 1.0 | 1.9 | 2.5 | V |
| Drain-Source On-Resistance | R _{DS(on)} | V _{GS} = 10V, I _D = 20A | -- | 6.6 | 8.0 | mΩ |
| | | V _{GS} = 4.5V, I _D = 20A | -- | 8.1 | 9.5 | |
| Forward Transconductance | g _{FS} | V _{GS} = 5V, I _D = 20A | -- | 53 | -- | S |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} = 0V, V _{DS} = 50V, f = 1.0MHz | -- | 2915 | -- | pF |
| Output Capacitance | C _{oss} | | -- | 380 | -- | |
| Reverse Transfer Capacitance | C _{rss} | | -- | 9 | -- | |
| Total Gate Charge | Q _g | V _{DD} = 50V, I _D = 20A, V _{GS} = 10V | -- | 50 | -- | nC |
| Gate-Source Charge | Q _{gs} | | -- | 8 | -- | |
| Gate-Drain Charge | Q _{gd} | | -- | 10 | -- | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} = 50V, I _D = 20A, R _G = 1.6Ω | -- | 12 | -- | ns |
| Turn-on Rise Time | t _r | | -- | 9 | -- | |
| Turn-off Delay Time | t _{d(off)} | | -- | 27 | -- | |
| Turn-off Fall Time | t _f | | -- | 7 | -- | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Body Diode Current | I _S | T _C = 25°C | -- | -- | 70 | A |
| Body Diode Voltage | V _{SD} | T _J = 25°C, I _{SD} = 20A, V _{GS} = 0V | -- | -- | 1.2 | V |
| Reverse Recovery Charge | Q _{rr} | I _F = 20A, V _{GS} = 0V di/dt=100A/us | -- | 87 | -- | nC |
| Reverse Recovery Time | T _{rr} | | -- | 49 | -- | ns |

Notes

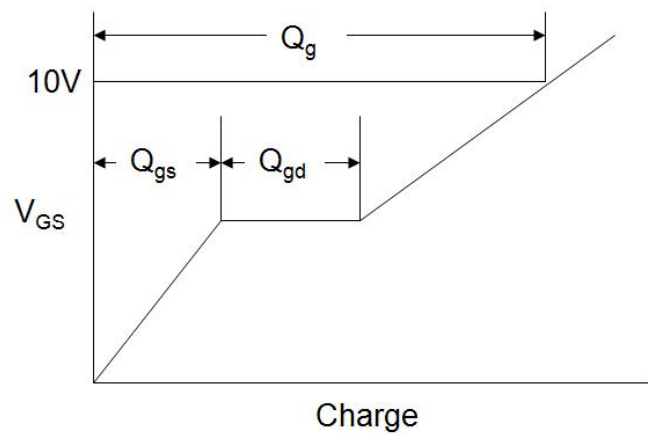
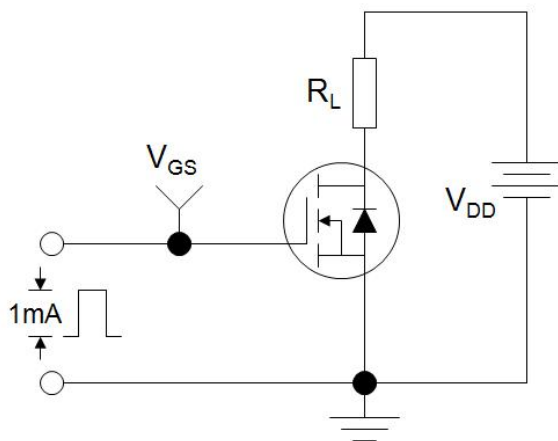
1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition : $T_J = 25^\circ\text{C}, V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$

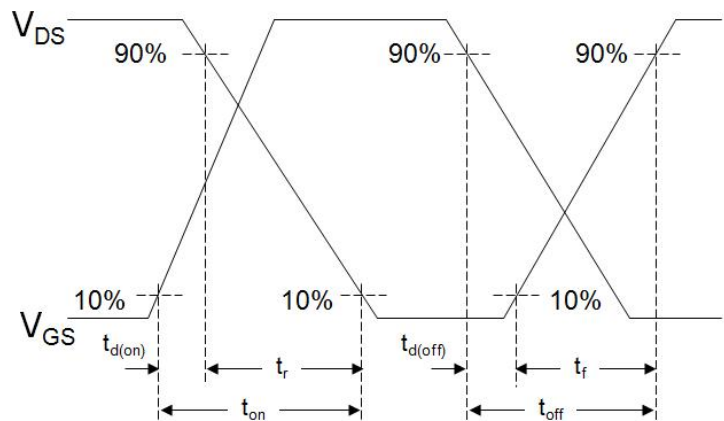
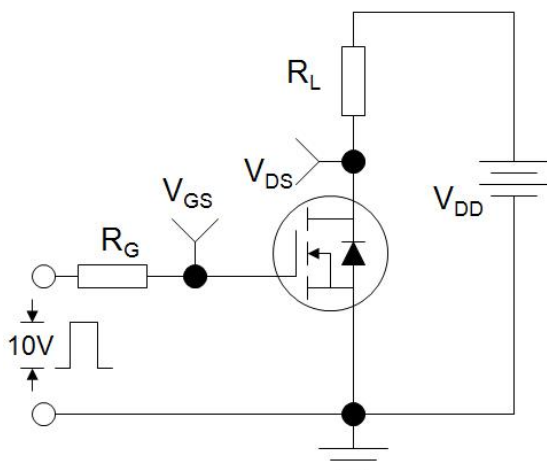
The table shows the minimum avalanche energy, which is 400mJ when the device is tested until failure

3. Identical low side and high side switch with identical R_G

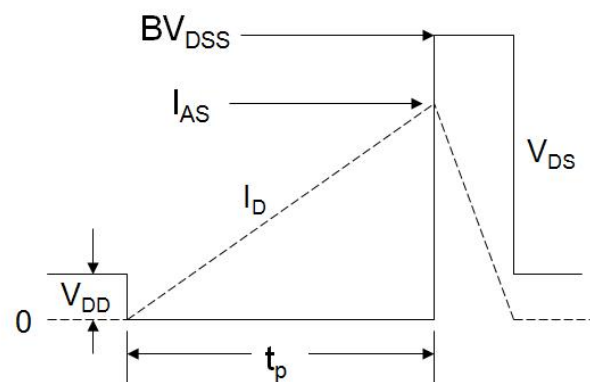
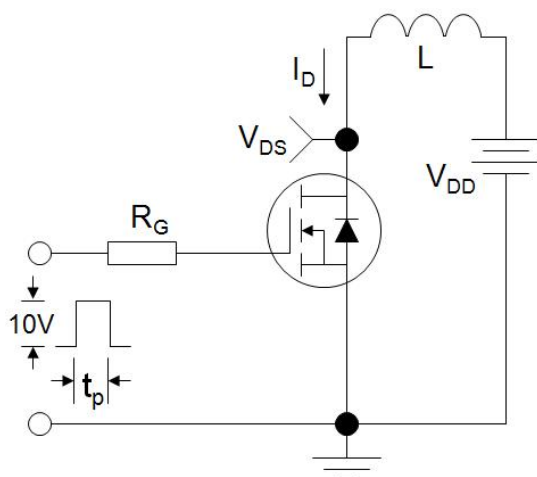
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

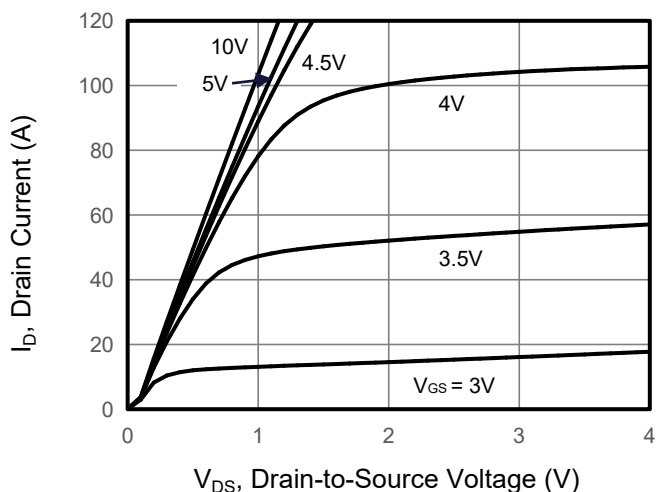


Figure 2. Transfer Characteristics

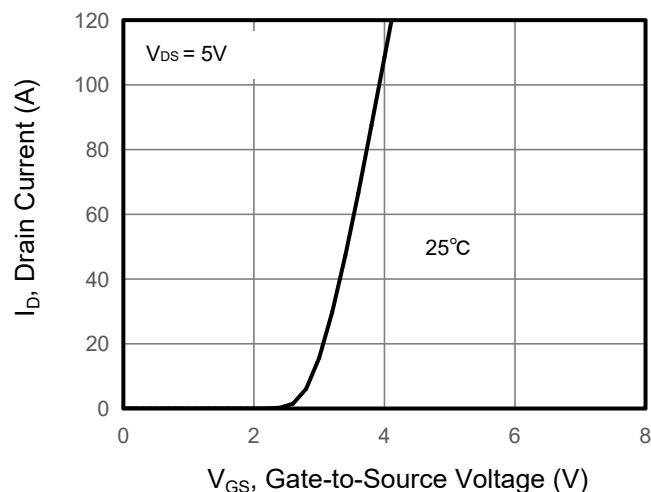


Figure 3. Drain Source On Resistance

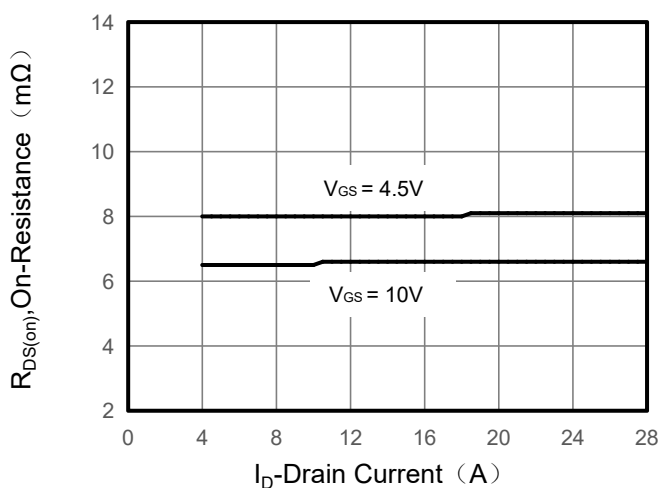


Figure 4. Gate Charge

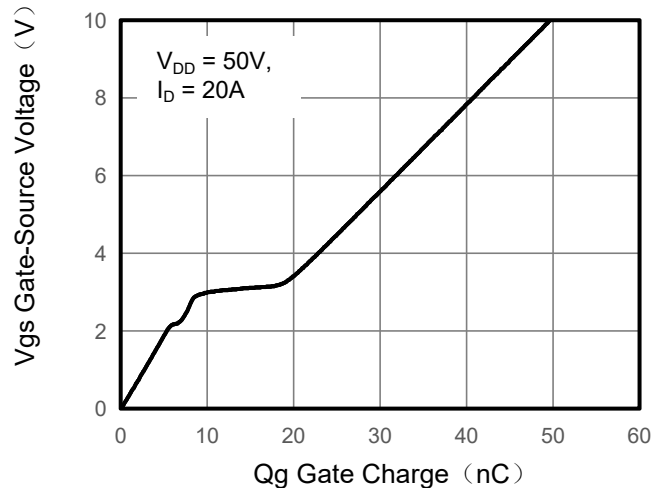


Figure 5. Capacitance

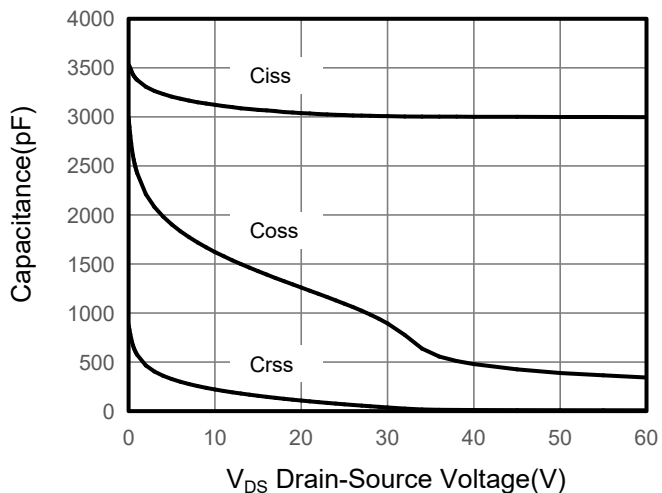
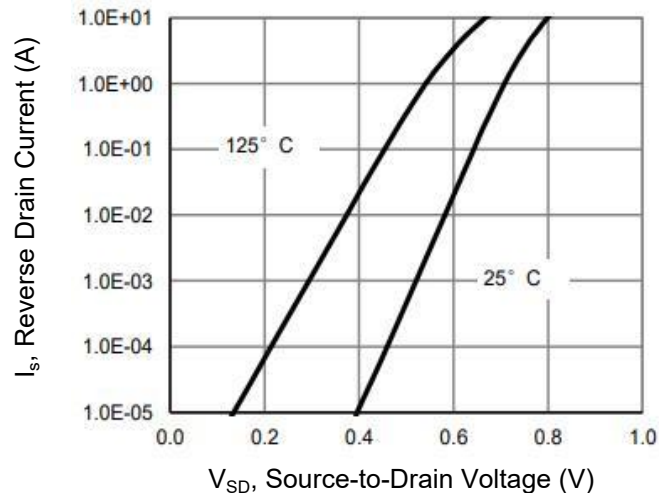


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

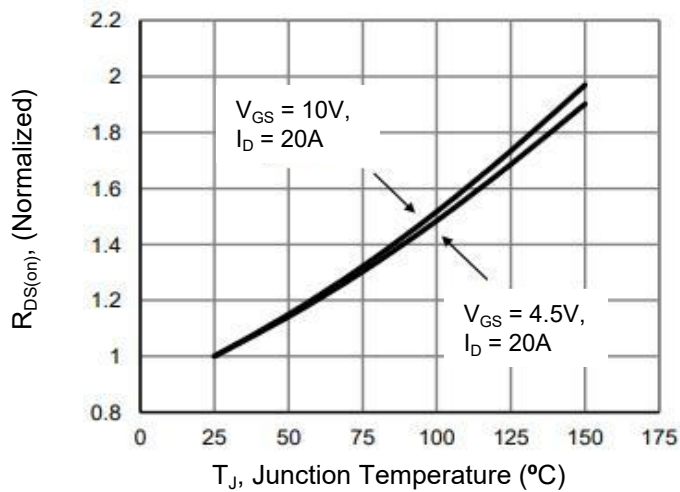


Figure 8. Safe Operation Area

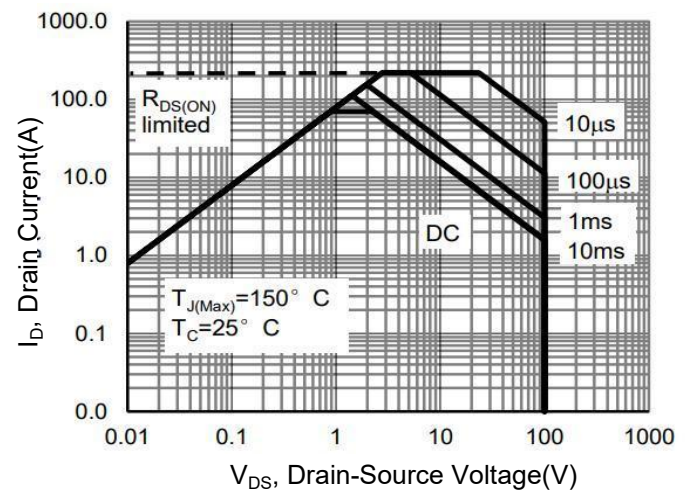
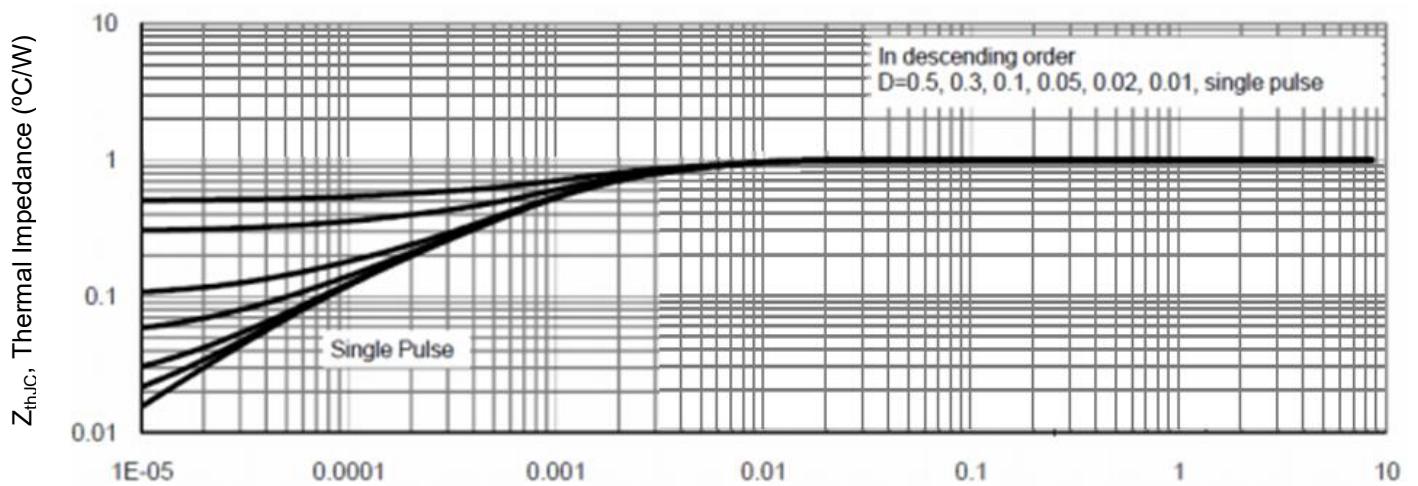
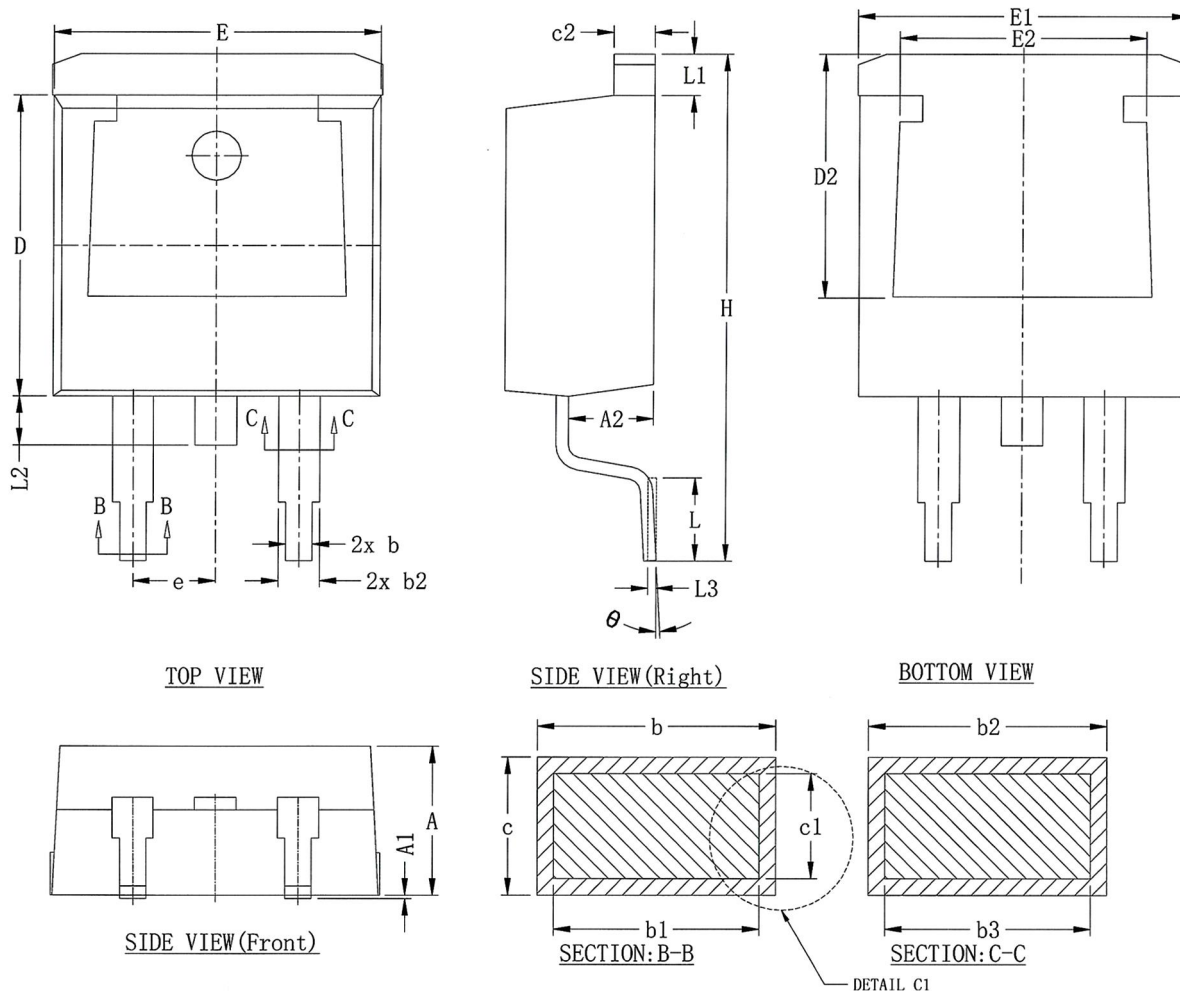


Figure 9. Normalized Maximum Transient



TO-263 Package Information



| DIM SYMBOL | MIN. | NOM. | MAX. | DIM SYMBOL | MIN. | NOM. | MAX. |
|---------------|-------|-------|-------|---------------|------------|--------|--------|
| A | 4.450 | 4.550 | 4.650 | D2 | 7.215 | 7.415 | 7.615 |
| A1 | 0.000 | — | 0.150 | E | 9.900 | 10.000 | 10.100 |
| A2 | 2.500 | 2.600 | 2.700 | E1 | 9.900 | 10.100 | 10.300 |
| b | 0.753 | 0.853 | 0.953 | E2 | 7.341 | 7.541 | 7.741 |
| b1 | 0.713 | 0.813 | 0.913 | e | 2.540 BSC. | | |
| b2 | 1.210 | 1.310 | 1.410 | H | 15.300 | 15.500 | 15.700 |
| b3 | 1.170 | 1.270 | 1.370 | L | 2.340 | 2.540 | 2.740 |
| c | 0.330 | 0.421 | 0.521 | L1 | 1.066 | 1.266 | 1.466 |
| c1 | 0.281 | 0.381 | 0.481 | L2 | 1.400 | 1.500 | 1.600 |
| c2 | 1.210 | 1.310 | 1.410 | L3 | 0.254 BSC. | | |
| D | 9.100 | 9.200 | 9.300 | θ | 0° | --- | 5° |